ABSTRACT

LEADFRAME COMPRISING TIN PLATING OR AN INTERMETALLIC LAYER FORMED THEREFROM

A method of producing a leadframe is provided comprising the steps of providing a substrate, plating the substrate with a layer of tin, plating a layer of nickel over the layer of tin, and thereafter plating one or more protective layers over the layer of nickel. The leadframe may thereafter be heated to produce one or more intermetallic layers comprising tin, which impedes the out–diffusion of copper from a base material of the leadframe to the surface thereof.

(FIG. 5)